

Abstract

Method for determining the arrangement of contact areas on the active top side of a semiconductor chip

In the case of a method according to the invention for determining the arrangement of contact areas on the active top side of a semiconductor chip arranged in or on a housing, firstly semiconductor chip data, contact area data, housing data and production data are read in, from which a model of an electronic device is then determined. This is followed by determining the arrangement of the contact areas in said model of the electronic device. The contact area arrangement data thus determined are provided for subsequent fabrication and/or design processes.

[figure 1]